

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: **Donald C. Abbott, et al.**

Serial No.: **09/733,718**

Filed: **12/08/2000**

For: **Leadframes for High Adhesion Semiconductor  
Devices and Method of Fabrication**

TI No.: **29679**

Art Unit: **2814**

Examiner: **Cao, Phat X.**

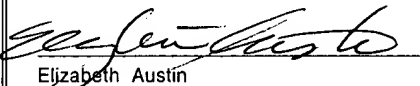
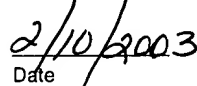
Conf. No.: **2496**

#11/Notice  
of  
appeal  
marsh  
3/6/03

NOTICE OF APPEAL

Assistant Commissioner For Patents  
Washington, DC 20231

Sir:

<b>MAILING CERTIFICATE UNDER 37 C.F.R. § 1.8(A)</b>	
I hereby certify that the above correspondence is being deposited with the US Postal Service as First Class Mail in an envelope addressed to: Assistant Commissioner for Patents, Washington, DC 20231.	
 Elizabeth Austin	 Date 2/10/2003

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Applicant hereby appeals to the Board of Appeals from the decision dated January 14, 2003, of the Primary Examiner finally rejecting Claims 1-6, 8-16, and 21-23.

Charge the fee of \$320.00 to the deposit account of Texas Instruments Incorporated, Account No. 20-0668. An original and two copies of this sheet are enclosed.

02/21/2003 RUCNDQF1 00000010 200668 09733718  
02 FC:1401 320.00 CH

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Respectfully submitted,



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